SteadySweep™ Pad Conditioner

entrepix

INCREASED PAD LIFE

Reduced Down Force: SteadySweep ™ results in a lower pad cut rate while achieving stable removal rate and wafer uniformity. The pneumatically applied force provides immediate response to pad surface changes. ***Lower pad cut rate and properly applied forces result in increased polish pad lifetime.***

Time Delay Intervals: SteadySweep ™ provides users the ability to program timed delays during a polish process. This is a feature that prolongs pad lifetime by raising the conditioner off the pad for a user defined time interval and returning the conditioner to the pad during the same wafer cycle. Traditional pad conditioners do not have this capability and users must either condition continuously, thereby prematurely wearing the pad, or shorten the conditioning cycle and suffer poor uniformity and repeatability . ***Flexible condition durations result in increased polished pad lifetime.***

ADVANCED PROCESS CAPABILITY

Segmented Sweep Profiles: SteadySweep ™ provides users the enhanced ability of pad profiling. The conditioners' travel across the pad is divided into 10 segments, each with a programmable dwell time. This creates conditioning zones which can be used to fine tune polish uniformity at the edges or center of the wafer by increasing or decreasing the conditioning rate of the pad in various zones. ***Definable conditioning capabilities result in optimized process uniformity and polish pad lifetime.***

Widest Available Process Range: SteadySweep ™ allows conditioning down forces from 0.5 to 20.0 pounds. This enhanced capability enables users to polish materials for today's most advanced applications that require pressures at the extremes of this range. ***SteadySweep ™ thereby extends the useful life of the***

FEATURES AND SPECIFICATIONS

Operational Modes	• Break-in (new pad) • In-situ (during polish) • Ex-situ (between polishes)
Process Benefits	• Process stability with reduced conditioning force • Time delay intervals • Segmented sweep profiles • Wider range of down force enables advanced films processing and extends useful production life of tool • Lowers overall cost of ownership
Down Force	• 0.5 to 20.0 pounds • Pneumatic applied pressure • Stable triple diaphragm regulator • No delay or lag in applied force control
Rotational Speed	• 0 to 200 rpm
Simplicity	• 5 minute calibration • Off-the-shelf components • Electronics interface on swing out panel • Compact design provides force at pad with only one pivot • Teflon coated to withstand wide pH range of slurries and create ease of cleaning

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